CLAIMS

I Claim,

1. A sink compound laminate modeling process is comprised of the following steps:

Step 1: Prepare sheet copper material in a thickness of 0.1~8.0 mm depending on the profile of the sink;

Step 2: Place the copper material in the molding cavity to such extent that the bottom of the copper material completely bound to the bottom layer of the molding cavity;

Step 3: The copper material is heated up to 360~650 ℃ and an inert gas is injected into the molding cavity or the molding cavity is maintained in vacuumed status to prevent oxidization taking place on the surface of the copper material; and

Step 4: The melting aluminum material is poured into the molding cavity using a gravity casting process to create a diffused binding to the interface between both of the copper and aluminum materials.

Finally, the aluminum material is cooled down and cured to avail a structure of a compound laminate of an integrated heterogeneous alloy of copper and aluminum in a given profile characterized by the crystals present in the interface between the copper and the aluminum materials.

2. A sink compound laminate modeling process as claimed in Claim 1, wherein, an inert gas is poured into the modeling cavity in the course of heating up the copper material to prevent oxidization taking place on the surface of the copper material.

3. A sink compound laminate modeling process as claimed in Claim 1, wherein, the modeling cavity is kept in vacuumed status during the course of heating up the copper material to prevent oxidization taking place on the surface of the copper material.

4. A sink compound laminate modeling process as claimed in Claim 1, wherein, the copper material relates to a strict copper.

5. A sink compound laminate modeling process as claimed in Claim 1, wherein, the copper material relates to a copper alloy.

6. A sink compound laminate modeling process as claimed in Claim 1, wherein, the sheet copper material may be provided in various shape including triangle and strip.

7. A sink compound laminate modeling process as claimed in Claim 1, wherein, the aluminum material related to a strict aluminum.

8. A sink compound laminate modeling process as claimed in Claim 1, wherein, the aluminum material relates to any aluminum alloy selected from a group comprised of AlSiCu, AlSiZn, AlSiMg, AlSiCuMg, AlGe, AlGeSi, AlCu, AlMn, AlMg, AlLi, AlSn, and AlPb.